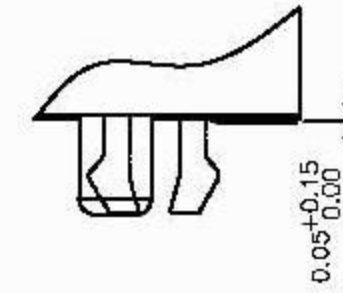
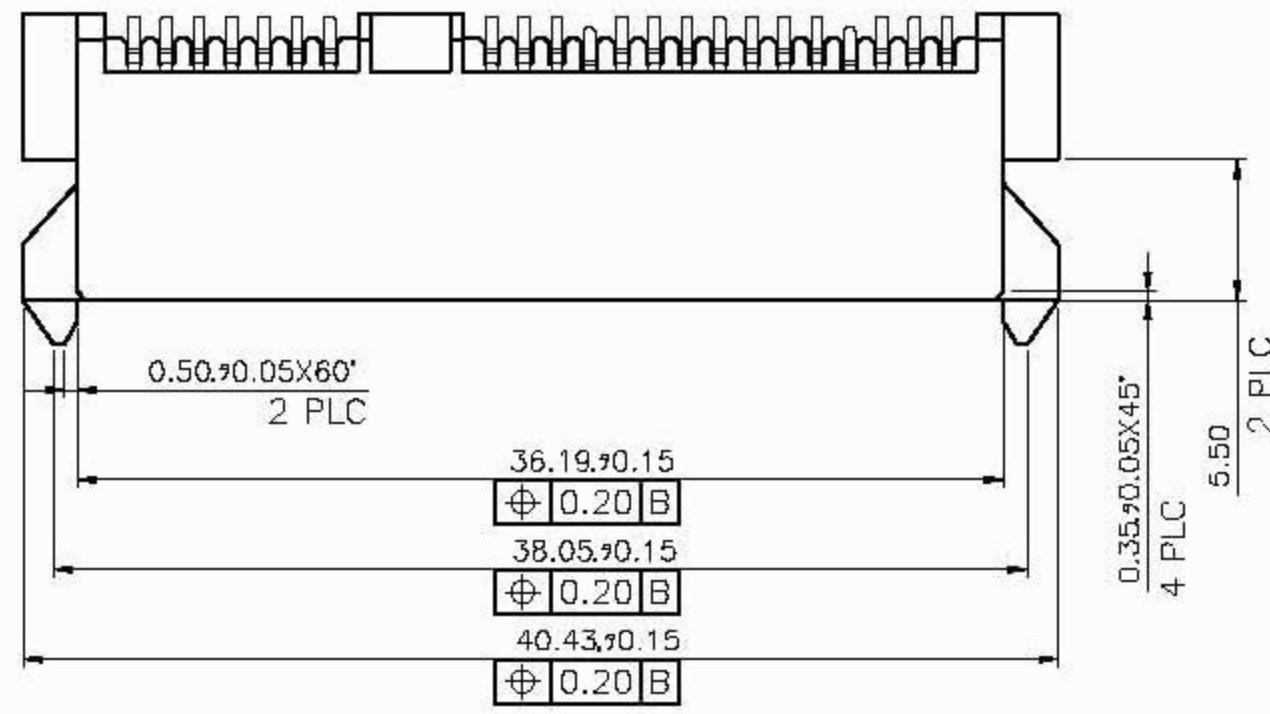


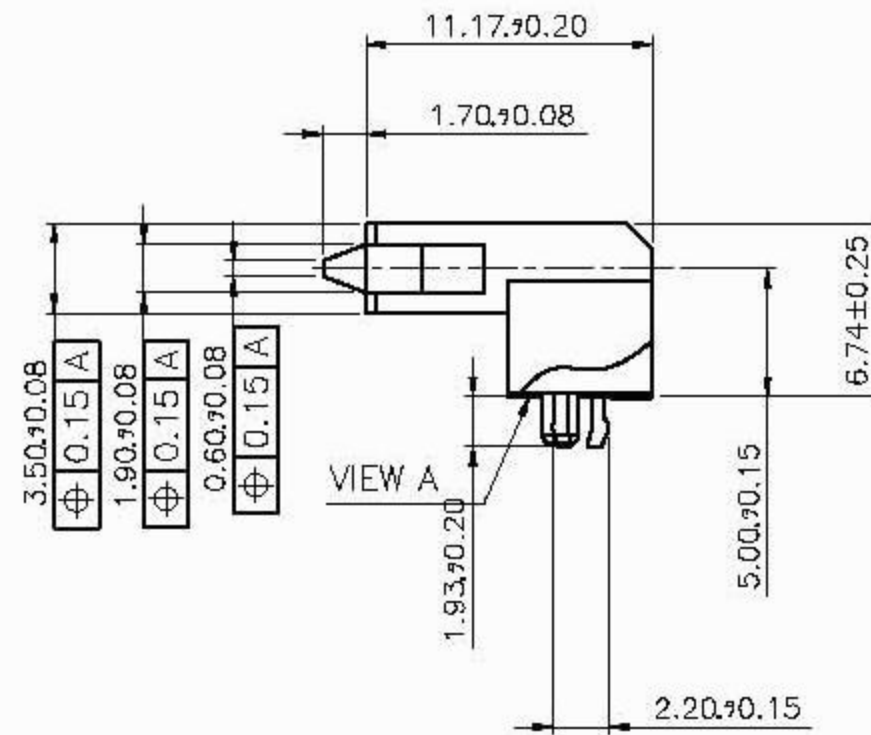
REV.	ECN NO.	DESCRIPTION	DRWN	APPD.	DATE
REV	ECN_NO.	DESCRIPTION	DR.	APPD.	DATE

SPEC:

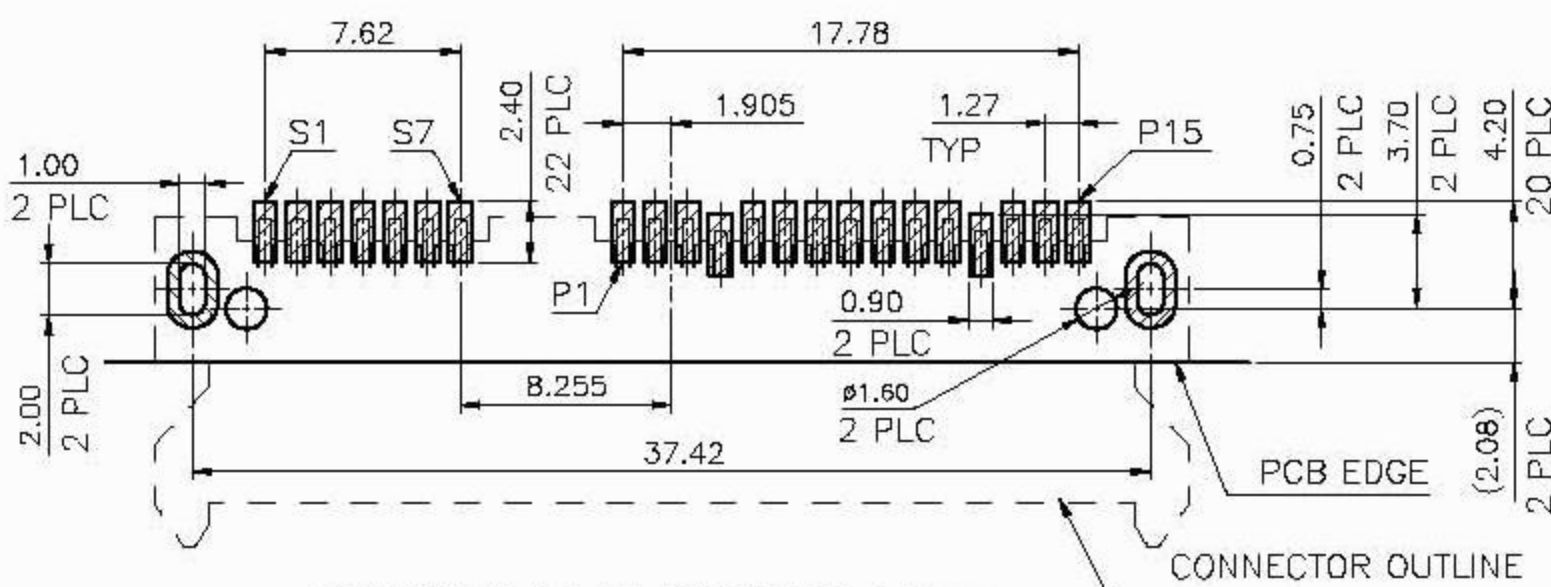
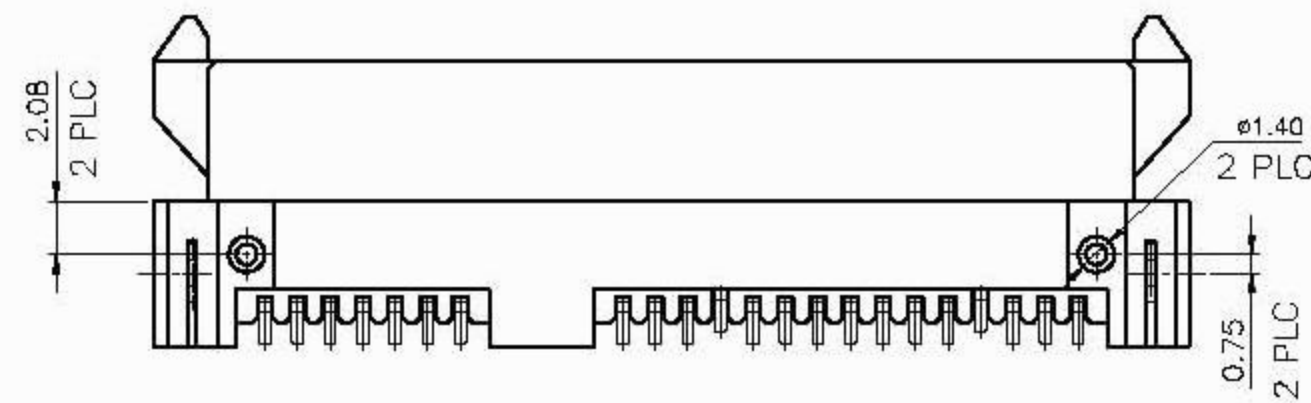
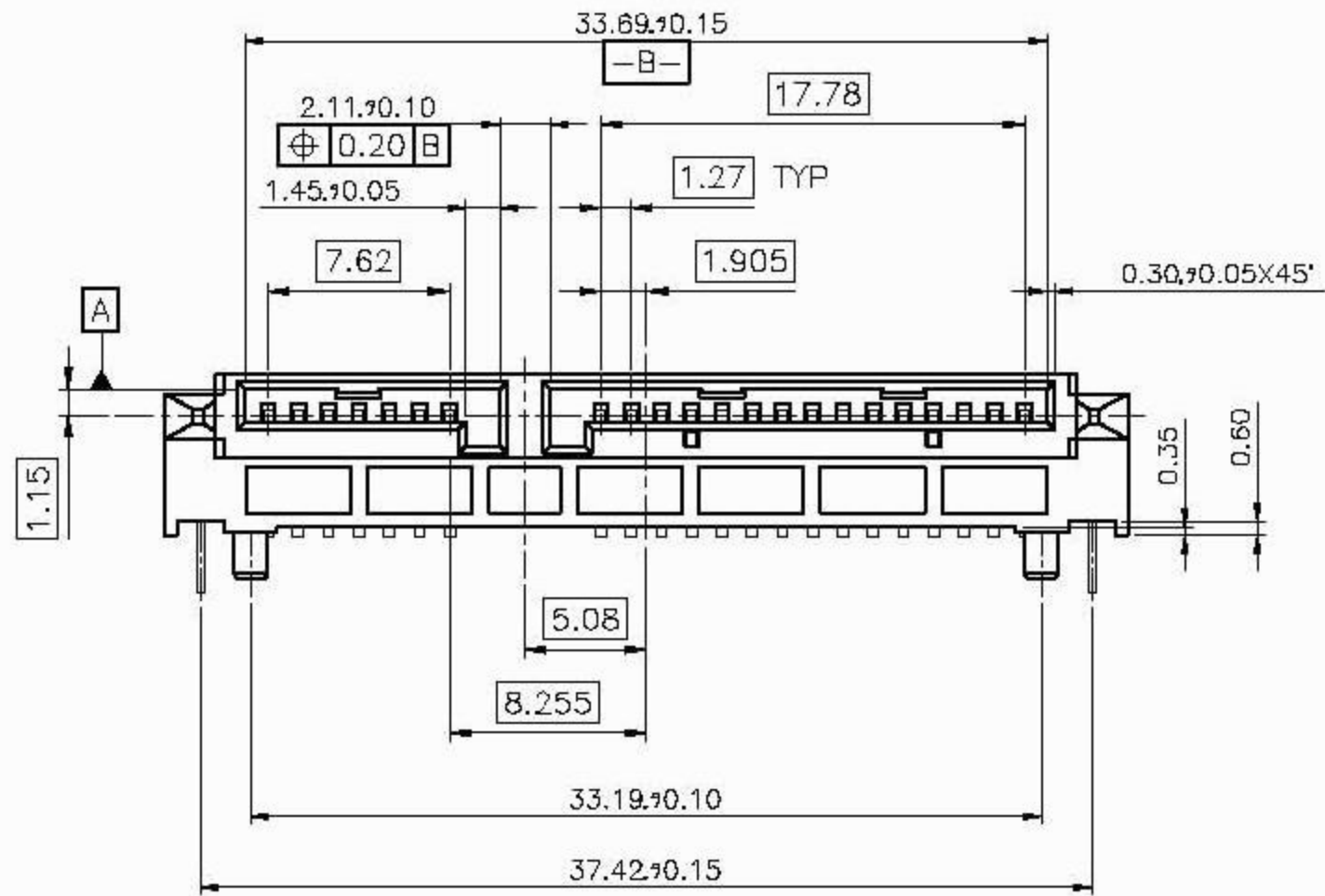
Current Rating: 3Amps
 Insulator Resistance: 5000mΩ Min
 Dielectric Withstanding: AC 500V
 Operating Temperature: -40° to+105°
 Contact Material: Copper alloy T=0.25
 Insulator Material: Polyester, UL 94V-0 LCP
 Finish :
 Gold/tin plating on contact area
 100u" min. Tin Plating on soldertails
 50u" min. nickel under plating over all tin,
 Max. Processing Temp:
 230C° for 30-60seconds(260C° for 10 secinds)



VIEW A
 SCALE 2:1



VIEW A



TOLERANCE: ±0.05, THICKNESS: 1.2mm
 RECOMMENDED PCB LAYOUT
 (TOP VIEW)

PART NAME	Q' TY	Material
CONTACT	22	C5191R-H, GOLD FLASH
BOARDLOCKS	2	C2680R-H, TIN 100μ"
HOUSING	1	LCP+30%GF, BLACK

UNITS mm	SCALE SCALE	REV. REV.	SHEET PAGE
		DATE	D_DATE
GENERAL TOLERANCE		DR.	DESIGNER
0. 0.0 0.00 0°. 0.0°		CHK.	
		APPD.	

L&X 深圳市连欣科技有限公司			
TITLE SATA7+15P 板下6.74 SMT成品			
MAT'L MATERIAL		FINISH FINISH	
DWG.NO. DWG_NO.	C	PART NO. XUTS-22674-0127	SIZE A4

1

2

3

4

5

6

A

B

C

D